

IN THE ABSTRACT:

Please amend the abstract as follows:

~~The present invention provides a~~ A surface-mount SAW device configured to prevent sealing resin layer coated all over the top surface of a piezoelectric substrate from becoming charged even if the piezoelectric substrate forming the SAW device is made of a pyroelectric material. The SAW device is composed of ~~[[1]]~~ a mounting substrate ~~[[2]]~~; a SAW chip ~~[[15]]~~ provided with a piezoelectric substrate ~~[[18]]~~, an IDT electrode ~~[[17]]~~ formed on one surface of said piezoelectric substrate, and connection pads ~~[[16]]~~ connected via conductor bumps ~~[[10]]~~ to conductor traces ~~[[5]]~~; a flip chip mounted to the mounting substrate; and a sealing resin layer ~~[[21]]~~ coated all over the outer surface of the SAW chip flip-chip mounted on the mounting substrate and extended down to the top surface of the mounting substrate to define an airtight space ~~[[S]]~~ between the IDT electrode and the mounting substrate; and wherein ~~the crystal structure of the piezoelectric substrate belongs to any one of point groups  $C_4$ ,  $C_2$ ,  $C_6$ ,  $C_{2v}$ ,  $C_4$ ,  $C_{4v}$ ,  $C_3$ ,  $C_{3v}$ ,  $C_6$  and  $C_{6v}$  in terms of Schoenflies symbols; characterized in that the~~ electrical conductivity of the piezoelectric substrate is increased to suppress charging of the sealing resin layer.